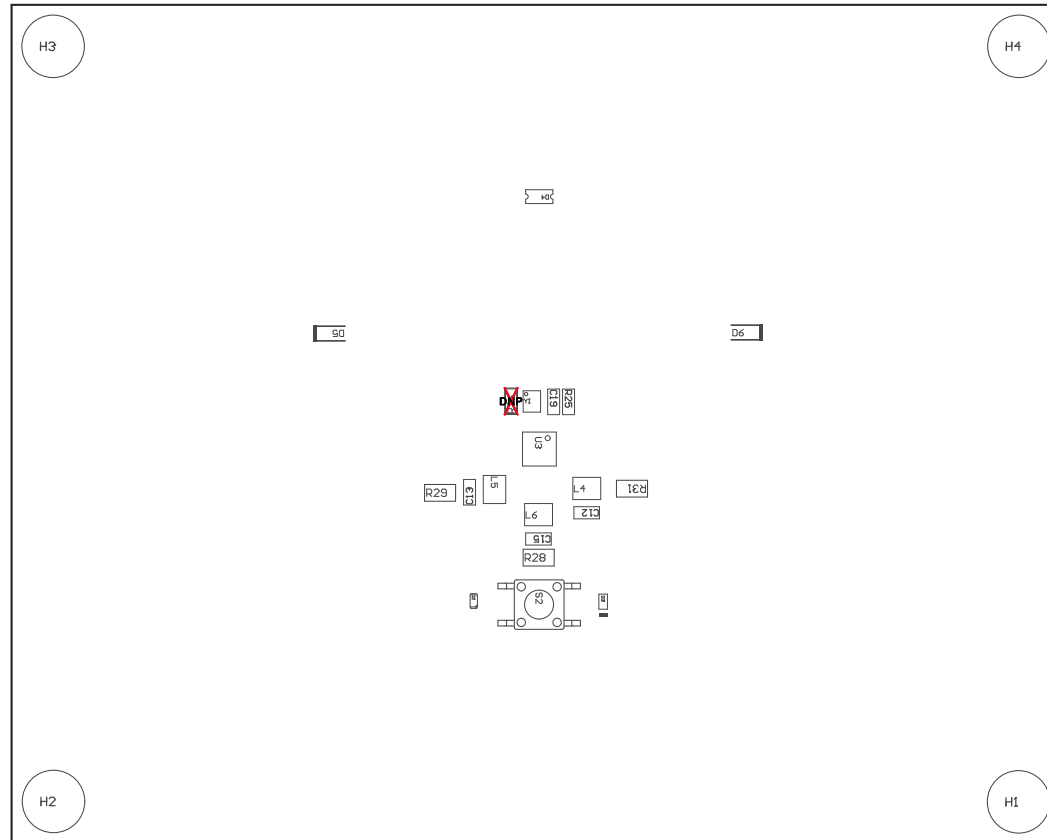
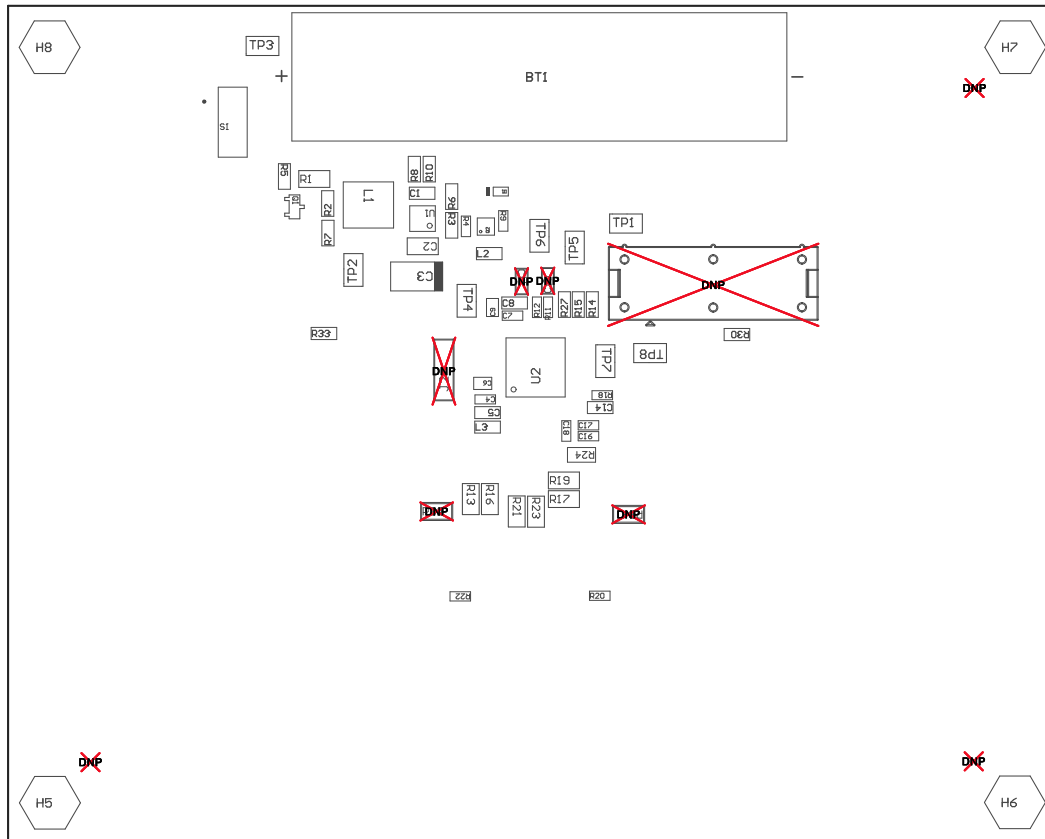


Z21 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 Z22 ■Provide H1, H2, H3, H4, H5, H6, H7, H8 as loose parts.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-00466		
PLOT NAME = Top Assembly Drawing	GENERATED : 9/29/2015 12:48:58 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #:	REV: A	SUN REV: Not In VersionControl
	TID #: TIDA-00466		
PLOT NAME = Bottom Assembly Drawing	GENERATED	: 9/29/2015 12:48:58 PM	TEXAS INSTRUMENTS

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